



### CST60P02D P-Ch 20V Fast Switching MOSFETs

- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

#### CST60P02D Product Summary



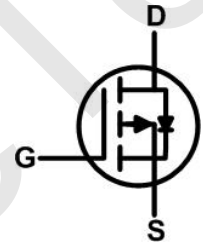
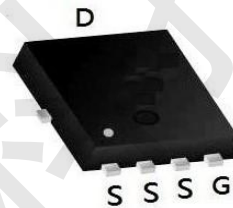
BVDSS	RDSON	ID
-20V	6mΩ	-60A

#### CST60P02D Description

The CST60P02D is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The CST60P02D meet the RoHS and Green Product requirement with full function reliability approved.

#### CST60P02D PDFN3333-8L Pin Configuration



#### CST60P02D Absolute Maximum Ratings (T<sub>A</sub> = 25°C, unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V <sub>DS</sub>	-20	V
Gate-Source Voltage		V <sub>GS</sub>	±10	V
Continuous Drain Current	T <sub>C</sub> =25°C	I <sub>D</sub>	-60	A
	T <sub>C</sub> =100°C		-34.8	
Pulsed Drain Current <sup>1</sup>		I <sub>DM</sub>	-220	A
Single Pulse Avalanche Energy <sup>2</sup>		EAS	61.25	mJ
Total Power Dissipation	T <sub>C</sub> =25°C	P <sub>D</sub>	39	W
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C

#### CST60P02D Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	R <sub>θJA</sub>	38	°C/W
Thermal Resistance from Junction-to-Case	R <sub>θJC</sub>	3.2	°C/W



### CST60P02D P-Ch 20V Fast Switching MOSFETs

#### CST60P02D Electrical Characteristics (T<sub>J</sub> = 25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
<b>Static Characteristics</b>							
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-20	-	-	V	
Gate-body Leakage current	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±10V	-	-	±100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V	T <sub>J</sub> =25°C	-	-	-1	μA
			T <sub>J</sub> =100°C	-	-	-100	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-0.4	-	-1.0	V	
Drain-Source on-Resistance <sup>4</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -15A	-	6	8.2	mΩ	
			V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -10A	-	7.5		10
			V <sub>GS</sub> = -1.8V, I <sub>D</sub> = -8A	-	10.2		15
Forward Transconductance <sup>4</sup>	g <sub>fs</sub>	V <sub>DS</sub> = -5V, I <sub>D</sub> = -15A	-	78	-	S	
<b>Dynamic Characteristics<sup>5</sup></b>							
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -10V, V <sub>GS</sub> = 0V, f = 1MHz	-	3560	-	pF	
Output Capacitance	C <sub>oss</sub>		-	500	-		
Reverse Transfer Capacitance	C <sub>rss</sub>		-	430	-		
Gate Resistance	R <sub>g</sub>	f = 1MHz	-	11	-	Ω	
<b>Switching Characteristics<sup>5</sup></b>							
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -10V, I <sub>D</sub> = -15A	-	43	-	nC	
Gate-Source Charge	Q <sub>gs</sub>		-	7.9	-		
Gate-Drain Charge	Q <sub>gd</sub>		-	11.2	-		
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>GS</sub> = -4.5V, V <sub>DD</sub> = -10V, R <sub>G</sub> = 3Ω, I <sub>D</sub> = -15A,	-	14.5	-	ns	
Rise Time	t <sub>r</sub>		-	20.2	-		
Turn-off Delay Time	t <sub>d(off)</sub>		-	93	-		
Fall Time	t <sub>f</sub>		-	161	-		
Body Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = -15A, dI <sub>F</sub> /dt = 100A/μs	-	28	-	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>		-	25.7	-	nC	
<b>Drain-Source Body Diode Characteristics</b>							
Diode Forward Voltage <sup>4</sup>	V <sub>SD</sub>	I <sub>S</sub> = -1A, V <sub>GS</sub> = 0V	-	-	-1.2	V	
Continuous Source Current	I <sub>S</sub>	T <sub>C</sub> =25°C	-	-	-60	A	

#### Notes:

1. Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C.
2. The EAS data shows Max. rating . The test condition is V<sub>DD</sub>= -25V, V<sub>GS</sub>= -10V, L= 0.1mH, I<sub>AS</sub>= 35A.
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
5. This value is guaranteed by design hence it is not included in the production test.



CST60P02D Typical Characteristics

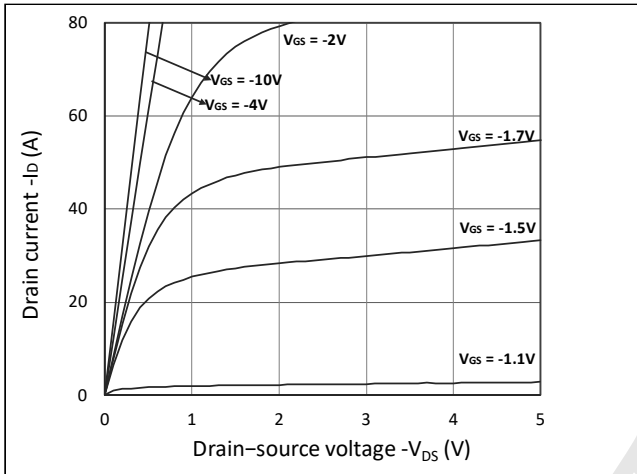


Figure 1. Output Characteristics

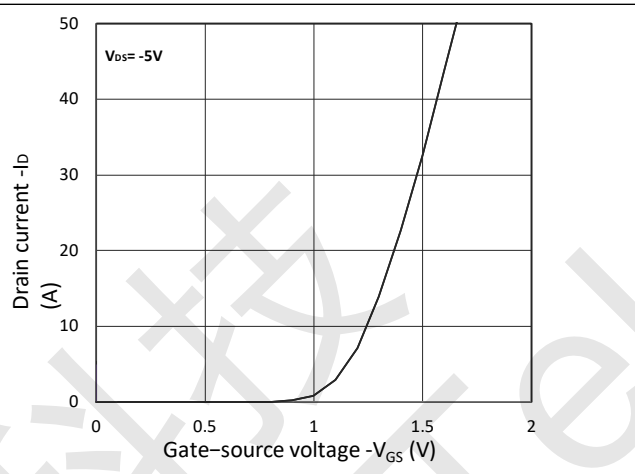


Figure 2. Transfer Characteristics

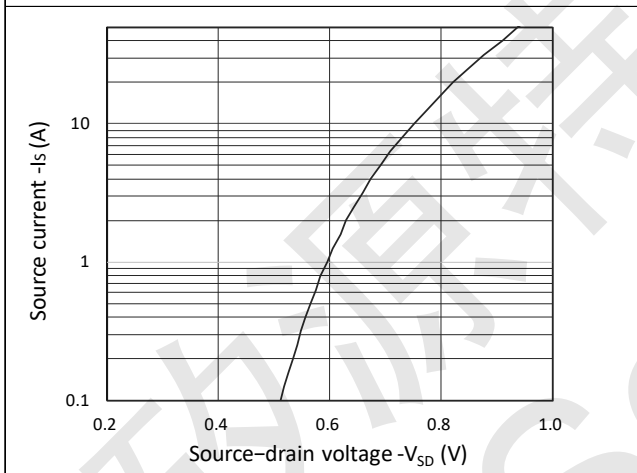


Figure 3. Forward Characteristics of Reverse

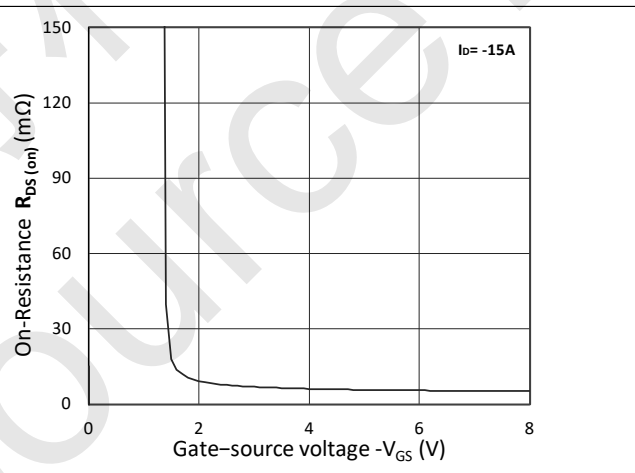


Figure 4.  $R_{DS(ON)}$  vs.  $V_{GS}$

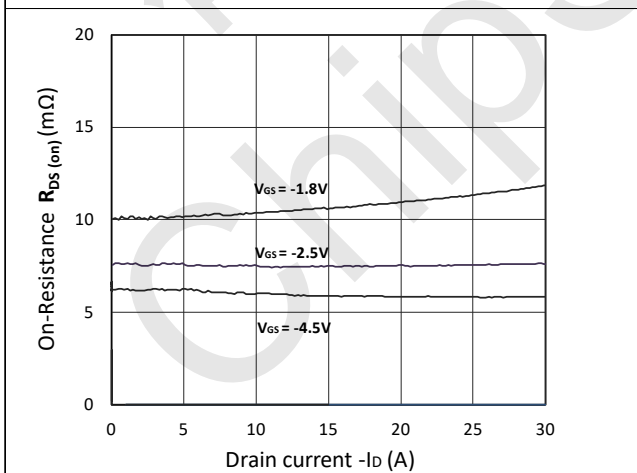


Figure 5.  $R_{DS(ON)}$  vs.  $I_D$

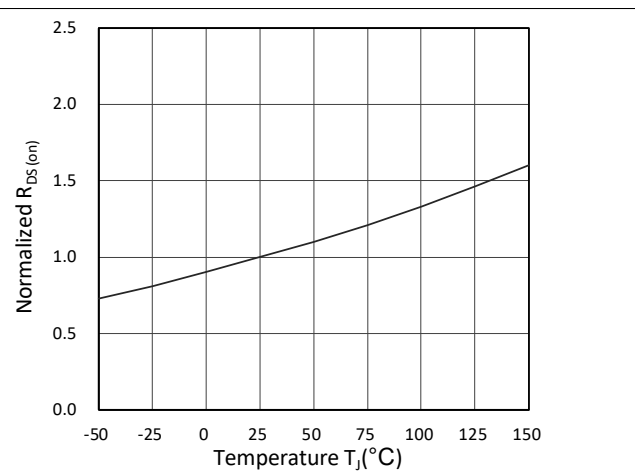


Figure 6. Normalized  $R_{DS(ON)}$  vs. Temperature



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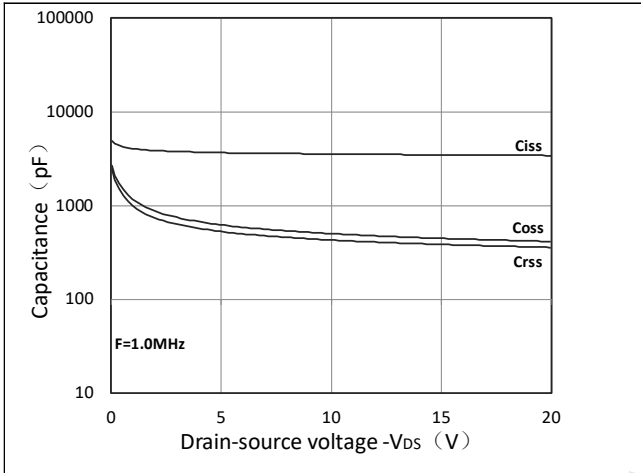


Figure 7. Capacitance Characteristics

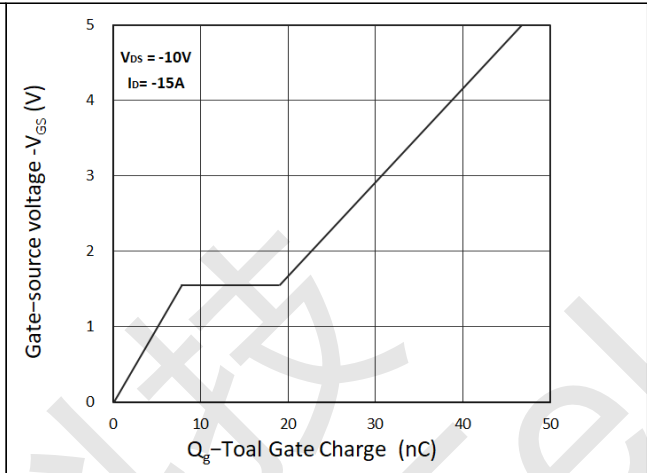


Figure 8. Gate Charge Characteristics

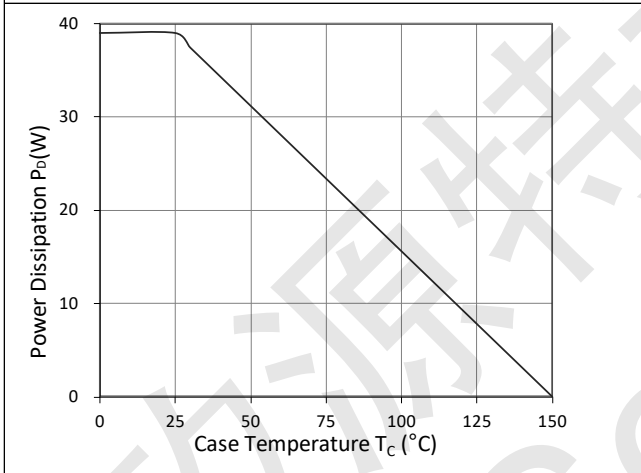


Figure 9. Power Dissipation

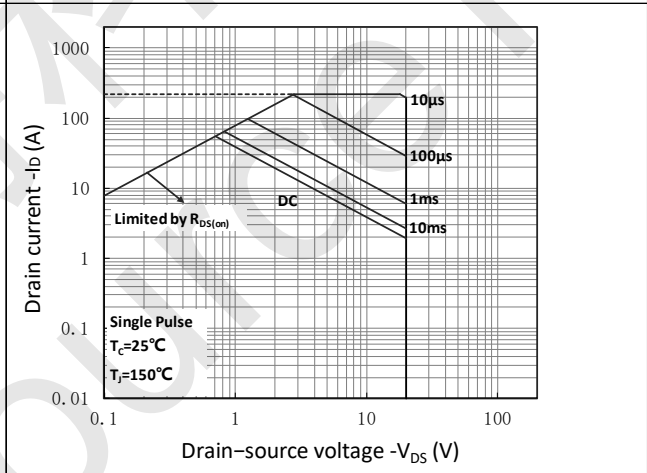


Figure 10. Safe Operating Area

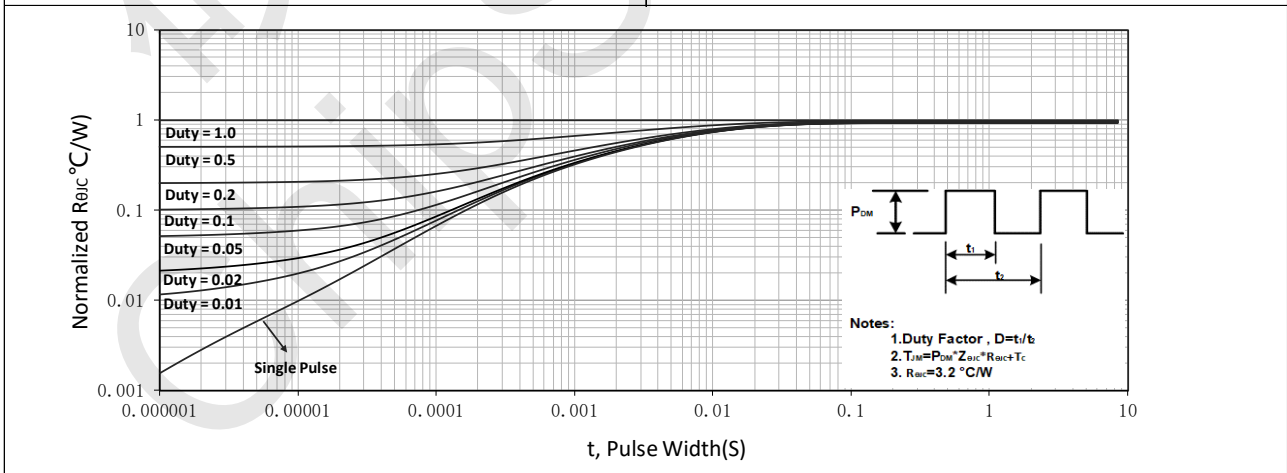


Figure 11. Normalized Maximum Transient Thermal Impedance



CST60P02D Test Circuit

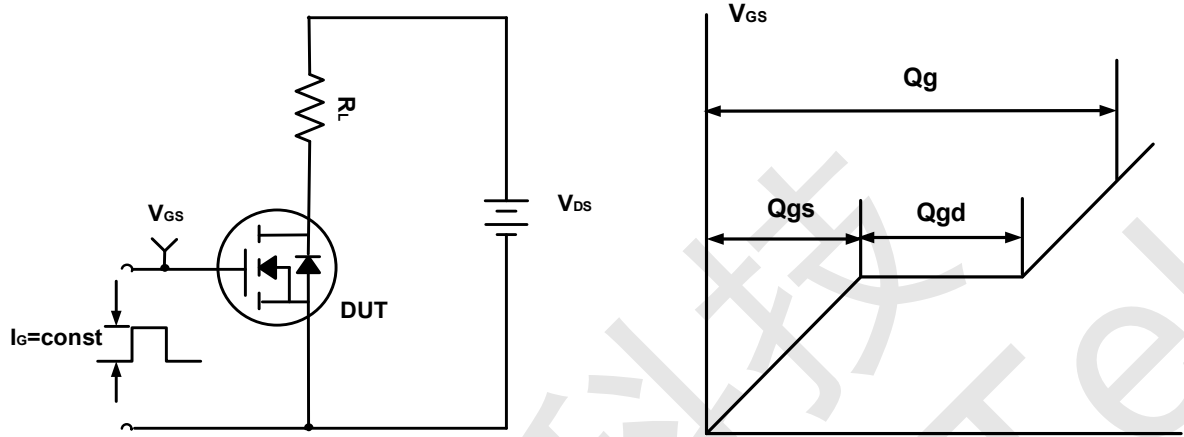


Figure A. Gate Charge Test Circuit & Waveforms

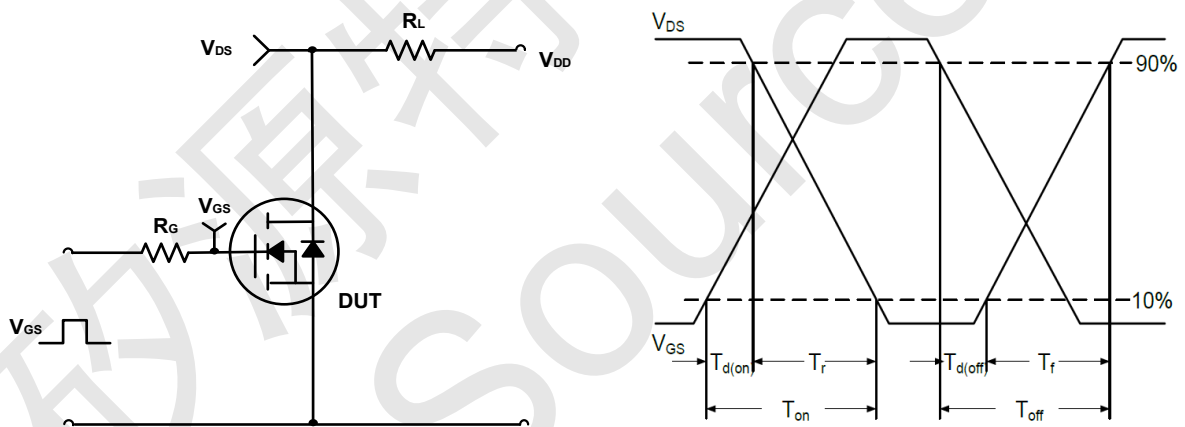


Figure B. Switching Test Circuit & Waveforms

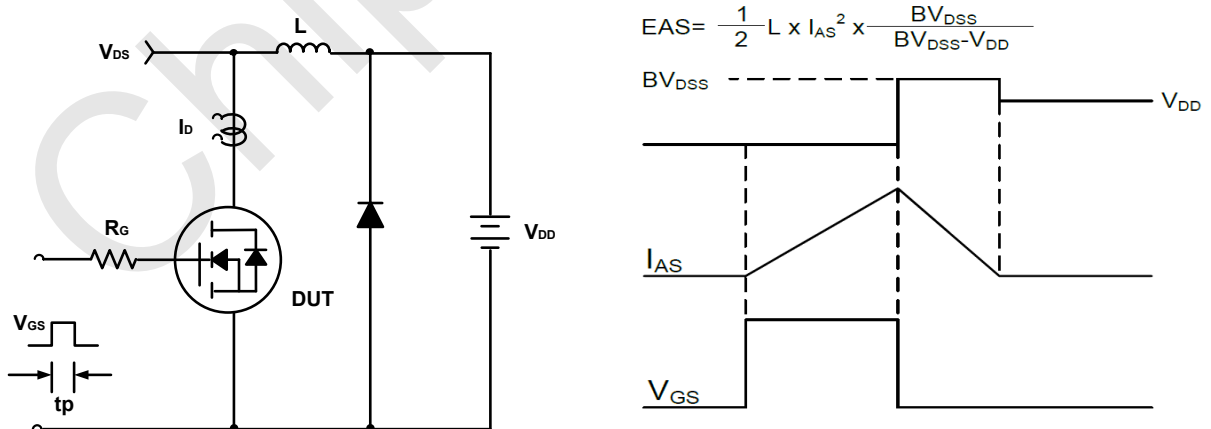
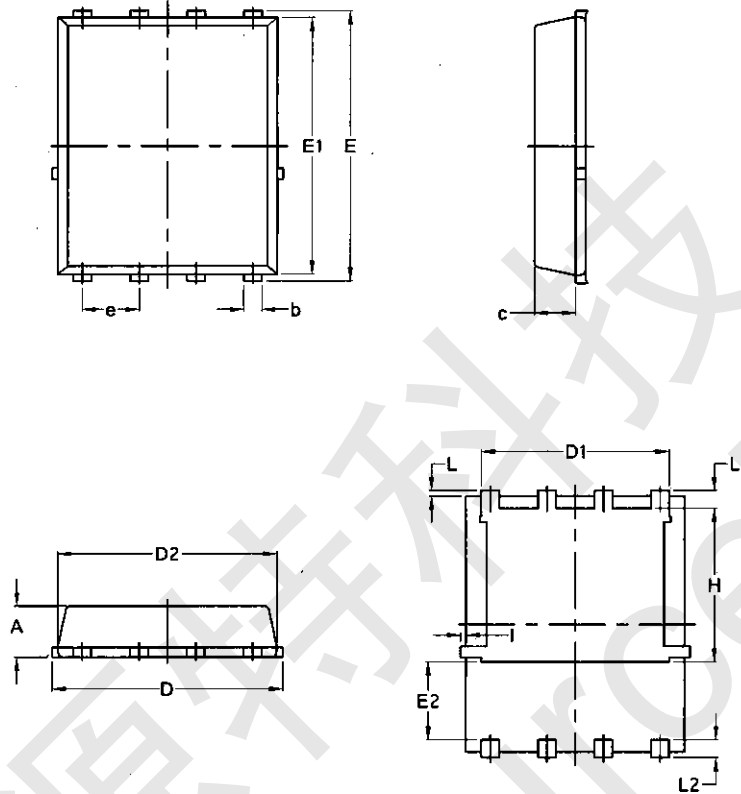


Figure C. Unclamped Inductive Switching Circuit & Waveforms



CST60P02D Package Mechanical Data-PDFN3333-8L-Single



COMMON DIMENSIONS

(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	0.70	0.80	0.90
A1	0.00	0.03	0.05
b	0.24	0.30	0.35
c	0.10	0.15	0.20
D	3.25	3.32	3.40
D1	3.05	3.15	3.25
D2	2.40	2.50	2.60
E	3.00	3.10	3.20
E1	1.35	1.45	1.55
e	0.65 BSC.		
H	3.20	3.30	3.40
L	0.30	0.40	0.50
L1	0.10	0.15	0.20
L2	1.13 REF.		